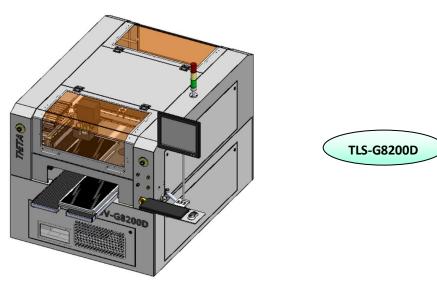
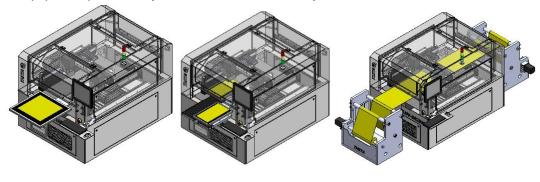


Double Station UV Laser Cutting Machine



Characteristics:

- Laser Source and Optical System: Use diode-pumped UV Laser source with high beam quality, high peak power and short pulse width, which can achieve "cold "processing to reduce the HAZ. Optimized optical transmission system with low power consumption, small focused spot size, high beam quality to ensure the reliability and consistency of the quality.
- 2. Motion System: Gantry structure with dual linear motor driven, closed loop control motion system with high resolution optical ruler to ensure the positioning accuracy and repeatability.
- 3. Machine vision system: High resolution camera with self-developed image processing algorithm to correct common material errors and ensure accuracy of processed products.
- 4. Natural Granite Platform: Natural and massive granite base reduces the inertia vibration of the table during start-up, shut-down and acceleration. At the same time, it maintains structure size long-term stability.
- 5. Software: With intelligent processing platform software-Thetalaser, which is a smart laser micromachining application platform, user-friendly easy to operate and enabling customized software modules.
- 6. Flexible feeding mode: compatible with large format material feeding mode, duplex alternating feeding mode, roll-to-roll feeding mode and on-line feeding mode. Meet OEM, mass production and other production needs, both short and long term equipment productivity and investment efficiency.



TLS-G8200S

TLS-G8200D

TLS-G8200R

THETA Kunshan Theta Micro Co., Ltd.

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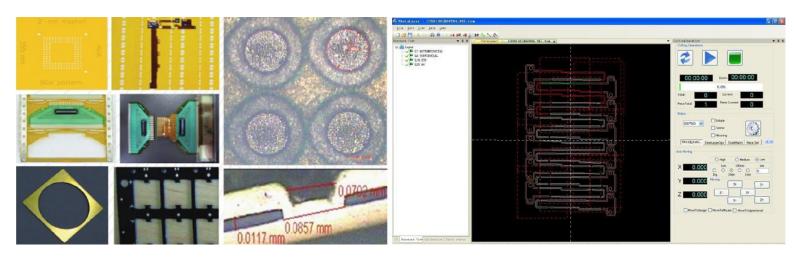
Application Range:

- Cutting and de-panelizing of FPC, rigid PCB, flexible-rigid PCB and baseboard of chip package.
- De-panelizing assembled flexible or rigid PCB.
- Precisely cutting thin copper foil, pressure sensitive adhesive, PP, acrylic sheet, polyimide film, etc.
- Precisely cutting ITO thin film, glass, organic thin film, special metal sheet, wafer and sapphire, etc.

Specification: (3Sigma)

Model	TLS-G8200D
Range of X/Y	600×800mm
Accuracy of X/Y	<±5µm
Repeatability of X/Y Axis	±1μm
Cutting Area	300mm×600mm(dual station),600mm*600mm(single station)
X/Y moving speed	1000mm/s max
Laser power	10W(8W, 12W optional)
Laser Wavelength	355nm
Laser Repetition Rate	30-130KHz
Operating Temperature	23±3°C
Operation Humidity	20%~70%RH(no dew)
Input Data Format	Gerber, DXF, HPGL, Sieb&Meyer, Excellon, PCB
Input Voltage	380VAC±10%, 50/60Hz; 220VAC±10%, 50/60Hz
Power Consumption	2.5KW
Compressed Air Pressure	0.5Mpa≤P≤1.5Mpa
Machine Size(LxWxH)	1400mmx2400mmx1450mm
Weight	2000Kg
Origin	China

Sample



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